

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Cancelled)
2. (Currently Amended) The apparatus of claim ~~1~~10 wherein the grooves are uniformly spaced over the polishing surface.
3. (Currently Amended) The apparatus of claim ~~1~~10 wherein the grooves have a depth between about 0.02 and 0.05 inches.
4. (Original) The apparatus of claim 3 wherein the grooves have a depth of approximately 0.03 inches.
5. (Currently Amended) The apparatus of claim ~~1~~10 wherein the grooves have a width between about 0.015 and 0.04 inches.
6. (Original) The apparatus of claim 5 wherein the grooves have a width of approximately 0.02 inches.
7. (Currently Amended) The apparatus of claim ~~1~~10 wherein the grooves have a pitch between about 0.09 and 0.24 inches.
8. (Original) The apparatus of claim 7 wherein the grooves have a pitch of approximately 0.12 inches.

9. (Currently Amended) The apparatus of claim ~~1~~10, further comprising an actuator to urge the substrate and the belt into contact with one another for polishing.

10. (Currently Amended) ~~The apparatus of claim 1~~ A chemical mechanical polishing apparatus, comprising:

a substrate holder to hold a substrate;

a polishing belt having a polishing surface to contact at least a portion of the substrate held by the substrate holder while the polishing belt is moving in a first direction in a generally linear path relative to the substrate, the polishing belt having a plurality of grooves formed therein, the grooves oriented substantially perpendicular to the first direction; and

a backing member positioned on a side of the polishing belt opposite the substrate holder;

wherein a fluid layer is interposed between the backing member and the polishing belt.

11. (Currently Amended) The apparatus of claim ~~1~~10 wherein the belt has a width at least as wide as the substrate holder.

12. (Currently Amended) The apparatus of claim ~~1~~10 wherein the belt is driven continuously during polishing.

13. (Currently Amended) The apparatus of claim ~~1~~10 wherein the belt is driven periodically between polishing operations.

14. (Currently Amended) The apparatus of claim ~~1~~10 wherein the belt is a continuous belt.

15. (Currently Amended) The apparatus of claim ~~1~~10 wherein the belt extends between a feed and a take-up roller.

16. Cancelled.

17. (Currently Amended) ~~The apparatus of claim 1 further comprising~~ A chemical mechanical polishing apparatus, comprising:

a substrate holder to hold a substrate;

a polishing belt having a polishing surface to contact at least a portion of the substrate held by the substrate holder while the polishing belt is moving in a first direction in a generally linear path relative to the substrate, the polishing belt having a first plurality of grooves formed therein, the first plurality of grooves oriented substantially perpendicular to the first direction and a second plurality of grooves oriented substantially perpendicular to the first plurality of grooves; and

a backing member positioned on a side of the polishing belt opposite the substrate holder.

18. (Original) ~~The apparatus of claim 1~~ A chemical mechanical polishing apparatus, comprising:

a substrate holder to hold a substrate;

a polishing belt having a polishing surface to contact at least a portion of the substrate held by the substrate holder while the polishing belt is moving in a first direction in a generally linear path relative to the substrate, the polishing belt having a plurality of grooves formed therein, the grooves oriented substantially perpendicular to the first direction wherein the grooves include only one have an arcuate shape; the arcuate shape being curved away from the first direction of motion; and

a backing member positioned on a side of the polishing belt opposite the substrate holder.

19-20. Cancelled.

21. (Original) A chemical mechanical polishing apparatus, comprising:

a substrate holder to hold a substrate;

a polishing belt having a polishing surface to contact at least a portion of the substrate held by the substrate holder, the polishing belt movable in a first direction in a generally linear path relative to the substrate, the polishing belt having a first plurality of substantially linear grooves and a second plurality of substantially linear grooves formed therein, the first plurality of grooves oriented substantially perpendicular to the second plurality of grooves; and

a backing member positioned on a side of the polishing belt opposite the substrate holder.

22. (Original) The apparatus of claim 21 wherein the first plurality of grooves is oriented substantially perpendicular to the first direction.

23. (Original) The apparatus of claim 21 wherein the first and second pluralities of grooves are oriented at about 45 degrees to the first direction.

24-25. (Cancelled)

26. (New) A substrate polishing article, comprising:

a polishing belt having a polishing surface configured to polish at least a portion of a substrate during polishing of the substrate, the polishing belt having a width and a length, wherein the length is greater than the width; and

a first plurality of grooves formed in the polishing surface, the grooves oriented substantially perpendicular to the length of the polishing belt and a second plurality of grooves oriented substantially perpendicular to the first plurality of grooves.

27. (New) The article of claim 26, wherein the first plurality of grooves includes substantially linear grooves and the second plurality of grooves includes substantially linear grooves.

28. (New) The article of claim 26, wherein the polishing belt is a continuous belt.

29. (New) The article of claim 26, wherein the polishing belt has a take-up end and a feed end.

30. (New) The article of claim 26, wherein the polishing belt comprises a layer including polyurethane.

31. (New) A substrate polishing article, comprising:
a polishing belt having a polishing surface configured to polish at least a portion of a substrate during polishing of the substrate, the polishing belt having a width and a length, wherein the length is greater than the width, the polishing belt having a plurality of grooves formed therein, the grooves oriented substantially perpendicular to the length of the polishing belt, wherein each groove includes only one arcuate shape that bows in a direction parallel to the length of the polishing pad.